

Title (en)
COPPER ALLOY SHEET

Title (de)
KUPFERLEGIERUNGSFOLIE

Title (fr)
FEUILLE D'ALLIAGE DE CUIVRE

Publication
EP 2508632 A4 20131218 (EN)

Application
EP 10834574 A 20101201

Priority
• JP 2009274893 A 20091202
• JP 2010071494 W 20101201

Abstract (en)
[origin: EP2508632A1] {Problems} To provide a Corson-based copper alloy sheet material which satisfies characteristics required of terminals and connectors, such as mechanical strength and bending property. {Means to solve} A copper alloy sheet material for electrical or electronic parts, which is composed of a copper alloy composition containing, in terms of mass%, any one or both of Ni or Co in an amount of 0.8 to 5%, and Si in an amount of 0.2 to 1.5%, with the balance being Cu and inevitable impurities, wherein an area ratio of grains having a deviation angle of less than 15° from the Cube orientation is controlled to less than 10%, and an area ratio of grains having a deviation angle of 15° to 30° from the Cube orientation is controlled to 15% or greater, and wherein the copper alloy sheet material has excellent mechanical strength and bending property.

IPC 8 full level
C22F 1/08 (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP KR)
C22C 9/00 (2013.01 - KR); **C22C 9/06** (2013.01 - KR); **C22F 1/08** (2013.01 - EP KR); **H01B 1/02** (2013.01 - KR); **H01B 1/026** (2013.01 - EP)

Citation (search report)
• [X1] WO 2009123159 A1 20091008 - FURUKAWA ELECTRIC CO LTD [JP], et al & EP 2270242 A1 20110105 - FURUKAWA ELECTRIC CO LTD [JP]
• See references of WO 2011068124A1

Cited by
US10358697B2; US10294554B2

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
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EP 10834574 A 20101201; CN 201080051566 A 20101201; JP 2010071494 W 20101201; JP 2011514943 A 20101201; KR 20127012667 A 20101201